



Material Content Data Sheet



Sales Product Name	TLE4209G			Issued		28. August 2013		
MA#	MA000982400							
Package	PG-DSO-14-22			Weight*		142.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.173	2.22	2.22	22199	22199
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		106	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8443	
	non noble metal	copper	7440-50-8	49.007	34.28	35.17	342841	351812
wire	noble metal	gold	7440-57-5	0.216	0.15	0.15	1510	1510
encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1206	
	plastics	epoxy resin	-	7.928	5.55		55462	
	inorganic material	silicondioxide	60676-86-0	78.074	54.62	60.29	546185	602853
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8578	8578
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7204	7204
glue	plastics	acrylic resin	-	0.184	0.13		1286	
	noble metal	silver	7440-22-4	0.652	0.46	0.59	4558	5844
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com